PRODUCT/PROCESS
CHANGE NOTIFICATION

PCN APMS/25/15686

Analog, Power, MEMS & Sensors (APMS)

ST Manufacturing Reshaping (Analog_FE+EWS BCD9 AG200toAG300_all): Qualification of ST Agrate 12 inches (Italy) as new FE location and ST Crolles (France) as new EWS Location for BCD9 products

Issue date: 25th November 2026

Description of the change

Following Corporate PCI 15383 (Early Notification), about Company reshaping program, please be informed that EWS (Electrical Wafer Sorting) of Analog products listed here below will be transferred from ST Agrate (Italy) to ST Crolles (France).

Change Summary:

	Former	New
EWS/Location	ST Agrate	ST Crolles

Traceability:

Internal Traceability – Date code-
Step tracked in ST production systems and available real time on demand

This report is a summary of the reliability trials performed in good faith by STMicroelectronics. This report does not imply for STMicroelectronics expressly or implicitly any contractual obligations other than as set forth in STMicroelectronics General Terms and Conditions of Sale.

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.

Affected products

Refer to Below table for involved Commercial Products.
Specific devices not expressly listed in this table are included in this change.

CP code involved in qualification		
L9026-B03N-TR	L9963E	L99DZ300-TR
L9026-YO-TR	L9963E-TR	L99DZ320TR
L9600	L9963-TR	L99LDLH32TR
L9600-TR-TX	L9965A-TR	L99PCUFA
L9601	L99BM114	L99PCUFAG
L9601-TR	L99BM114-TR	L99PCUFAG-TR
L9783-TR	L99BM218-TR	L99PCUFA-TR
L9784	L99DZ300	MAR9770L
L9785	L99DZ300GTR	MAR9770LTR
L9788A-TR	L99DZ300H	STSPIN32G4
L9963	L99DZ300HTR	STSPIN32G4TR

Dual die (one of the dice qualified)
Qualification on going
Qualified

Reason

Die manufacturing: ST manufacturing reshaping program - Corporate PCI - Early Notification.

Date of implementation

First shipments forecast: one month after Qualification completion date (see below qualification results date for reference).

Impact of change	
Form	Not Impacted
Fit	Not Impacted
Function	Not Impacted
Reliability	Not Impacted
Processibility	Not Impacted

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.

Qualification of the change (plan)

Qualification will be performed according to ST guidelines and ZVEI (ID SEM-TF01) for Automotive products.

		Compliant with ST internal spec and ZVEI Guideline Product and Process Changes (PCN) 5.0 (Automotive products)		
		Line readiness	ED (Electrical Distribution, Cpk, analysis *)	Parametric analysis (Yield, Bin to Bin *)
Product		•	•	•

* Comparing wafers in old vs. new location

Disposition of former products

Delivery of current products will be done until stock depletion.

Qualification results

Qualification report including qualification results is enclosed at the end of this document:

Qualification completion date: April-2026.

Sampling plan

Customer samples are not planned; the switch of production will occur at product validation.

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.

Qualification Report

Transfer of EWS (Electrical Wafer Sorting) from ST Agrate (Italy) to ST Crolles (France) for Analog products

General Information	
Commercial Product	See above list
Product perimeter	Analog
Product group	APMS
Maturity level	Qualified

Locations	
Diffusion Plant	Multiple
Assembly Plant	Multiple
Reliability Lab	N/A

Assessment	
Pass	X
Fail	

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.

Table of contents

1. APPLICABLE AND REFERENCE DOCUMENTS....6
2. GLOSSARY....6
3. RELIABILITY EVALUATION OVERVIEW....6
3.1. Objective....6
3.2. Conclusion....6
4. PRODUCT OR TEST VEHICLE CHARACTERISTICS....7
4.1. Device description....7
4.2. Package Outline.... **Error! Bookmark not defined.**
4.3. Construction note....8
5. TEST RESULTS SUMMARY....9
5.1. Lot information....9
5.2. Test plan and results summary....9
6. APPLICABLE AND REFERENCE DOCUMENTS.... **Error! Bookmark not defined.**
7. TESTS DESCRIPTION.... **Error! Bookmark not defined.**

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.

1. APPLICABLE AND REFERENCE DOCUMENTS

ZVEI	Change Standard Methodology

2. GLOSSARY

EWS	Electrical Wafer Sorting

3. RELIABILITY EVALUATION OVERVIEW

3.1. Objective

The objective of this report is to qualify the transfer of EWS (Electrical Wafer Sorting) from ST Catania (Italy) to ST Crolles for products detailed in PCN: Qualification plan conducted following ZVEI matrix as follow:

	ZVEI DEFAULT	ZVEI WITH CONDITIONS	ST SELECTED	REASON FOR EXCEPTION OF TESTS
AEC-Q101 Revision E	•	•	X	
Parametric Verification	•	•	X	No characterization planned as only EWS is transferred*
Parameter-Analysis: Comparison of current with changed device characterization, electrical distribution	•	•	X	

*Characterization is meant for Final Test transfer, not applicable for this EWS transfer

3.2. Conclusion

Qualification Plan requirements have been fulfilled without exception. Line readiness tests, Electrical Distribution, Cpk, Yield and Bin to Bin analysis and comparison have all shown positive results.
Based on these results, all devices are ready for the EWS transfer from ST Agrate to ST Singapore.

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.

4. PRODUCT OR TEST VEHICLE CHARACTERISTICS

4.1. Device description

Refer to ST specification:

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.

4.2. Construction note

	All parts listed in page 6
Wafer/Die fab. information	
Wafer fab manufacturing location	multiple
Technology	multiple
Wafer Testing (EWS) information	
Electrical testing manufacturing location	ST Crolles

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.

5. TEST RESULTS SUMMARY

5.1. Lot information

Lot #	Part Number	Comment
Lot 1	L9026-B03N-TR	
Lot 2	L9963E-TR	
Lot 3	L9963-TR	
Lot 4	L9963E-TR	
Lot 5	L9601-TR	
Lot 6	L9783-TR	
Lot 7	L99PCUFA	
Lot 8	L99PCUFAG	

Detailed results in below chapter will refer to these references.

5.2. Test plan

Qualification of the change (plan)

Qualification will be performed according to and ST guidelines and ZVEI (ID SEM-TF01) for Automotive products.

	Compliant with ST internal spec and ZVEI Guideline Product and Process Changes (PCN) 5.0 (Automotive products)		
	Line readiness	ED (Electrical Distribution, Cpk, analysis *)	Parametric analysis (Yield, Bin to Bin *)
Product	•	•	•

*comparing wafers in ol vs. new location

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.

5.3. results summary

Item	Qualification activity	Sample size	L9026-B03N-TR	L9963E-TR	L9963-TR	L9963E-TR	L9601-TR	L9783-TR	L99PCUFA	L99PCUFAG
EWS line transfer	Line readiness	1 lot	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS
	ED (Electrical Distribition, Cpk analysis)	1 full wafers	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS
	Parametric analysis (Yield, Bin to Bin)	1 full wafers	PASS	PASS	PASS	PASS	PASS	PASS	PASS	PASS

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.

TERMS OF USE

BY ACCEPTING THIS REPORT, YOU AGREE TO THE FOLLOWING TERMS OF USE:

This Document (the "Document") and all information contained herein is the property of STMicroelectronics ("ST"). The Document is believed to be accurate and reliable and is provided solely for the purpose of obtaining general information relating to an ST product.

Accordingly, you hereby agree to make use of this Document solely for the purpose of obtaining general information relating to the ST product. You further acknowledge and agree that this Document may not be used in or in connection with any legal or administrative proceeding in any court, arbitration, agency, commission or other tribunal or in connection with any action, cause of action, litigation, claim, allegation, demand or dispute of any kind.

This Document shall in no event be regarded as a warranty of a certain functionality, condition, or quality of the ST product. Accordingly, you agree that in no event will ST or its affiliates be liable to you for any direct, indirect, consequential, exemplary, incidental, punitive, or other damages, including lost profits, arising from or relating to your reliance upon or use of this Document. You further acknowledge and agree that the use of this Document in violation of these Terms of Use would cause immediate and irreparable harm to ST which could not adequately be remedied by damages. You therefore agree that injunctive relief is an appropriate remedy to enforce these Terms of Use.

Disclosure of this document to any non-authorized party must be previously authorized by ST only under the provision of a proper confidentiality contractual arrangement executed between ST and you and must be treated as strictly confidential.

At all times you will comply with the following rules:

- Do not copy or reproduce all or part of this document
- Keep this document locked away
- Further copies can be provided on a "need to know basis", Please contact your local ST Sales Office or document writer

Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement, including, without limitation, the warranty provisions thereunder.

In that respect please note that ST products are not designed for use in some specific applications or environments described in above mentioned terms and conditions.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

ST assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license, express or implied, to any intellectual property right is granted by ST herein.

ST and ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously contained in any prior version of this document.

©2025 STMicroelectronics - All rights reserved

This report and its contents shall not be disclosed to a third party without previous written agreement from STMicroelectronics.
© 2025 STMicroelectronics - All rights reserved. Refer to last page for terms of use.